

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-20. (Cancelled)

21. (Currently Amended) A regulating method of a storage water used for storage of a silicon wafer in water, wherein the concentration of Cu in the storage water, which is ultra pure water containing a chelating agent and a surfactant, is regulated to 0.01 ppb or less in the form of pit water in a waiting period between steps before a cleaning step in a silicon wafer production process.

22-25. (Cancelled)

26. (New): A regulating method of a storage water used for storage of a silicon wafer in water according to claim 21, wherein the silicon wafer to be stored has a hydrophobic surface.

27. (New): A regulating method of a storage water used for storage of a silicon wafer in water according to claim 21, wherein the silicon wafer is stored immediately after polishing.

28. (New): A regulating method of a storage water used for storage of a silicon wafer in water according to claim 26, wherein the silicon wafer is stored immediately after polishing.

29. (New): A regulating method of a storage water used for storage of a silicon wafer in water according to claim 21, wherein the chelating agent has a chelate compound production performance not lower than that of NTA.

Appl. No. 09/218,997

Attorney Docket No. 8565D-7213 (81839.0077)

Amdt. Dated: February 4, 2004

Customer No. 26021

Reply to Office Action of November 5, 2003

30. (New): A regulating method of a storage water used for storage of a silicon wafer in water according to claim 21, wherein the chelating agent is selected from the group consisting of NTA, EDTA, DTPA, CyDTA, salts thereof, and a mixture thereof.